

## IN THE SPECIFICATION

Please amend the specification as indicated below, in which matter deleted is shown by strike-through and matter added is underlined.

Please replace paragraph [0015] with the paragraph below:

[0015] Referring to Figure 4, ~~an exploded~~ a side view of an assembled optical unit 40 is shown supported by a semiconductor chip 42, which functions as an electro-optical interface for the optical unit 40. The optical unit 40 and chip 42 together define an electro-optical device for reading an optical disc (not shown). The optical unit 40 includes a lens element 12 mounted on a base element 22 in the manner indicated. In particular, extensions 44 and 46 of the rods 16 of lens element 12 fit into corresponding recesses 48 and 50 in the top surface 52 of the base element 22. Extensions 54 and 56 of the rods 24 of the base element 12 rest against the bottom surface 58 of the lens element 12. The mating of the rod extensions 44 and 46 in the respective recesses 48 and 50 achieves precise optical alignment of the lens element 12 with the base element 22. Similar recesses can be provided in the top surface of the semiconductor chip 42 for receiving the ends of the rods 24 on the bottom of the base element 22. Such recesses are preferred but optional. External fixtures can be used as an alternative assembly technique and adhesive can be applied to the mating surfaces. Figure 2 shows the base elements 22 without recesses for use in such an alternative assembly technique.

Please replace paragraph [0016] with the paragraph below:

[0016] Photodetectors 60 and 62 are provided at the upper surface 64 of the semiconductor chip 42. The photodetectors 60 and 62 are aligned with respective light beams 66 and 68 that originate from a light beam 70 returning from an optical disc (not shown) entering the lens element 12 through the back lens 32. The split-beam approach using a pair of photodetectors 60 and 62 as depicted in Figure 4 compares corresponding electrical signals within the chip 42 to eliminate unwanted signal noise. Band-pass filters (not shown) can also be added on surface portions 72 and 74 of the upper surface 52 of the base element 22 in the path of light beams 66 and 68 to filter out unwanted noise. Alternatively, the entire base element 22 can be clad with a thin film that filters out unwanted light noise.

Please replace paragraph [0017] with the paragraph below:

[0017] Mounted above the semiconductor chip 42 is a laser diode 76 that emits a laser light beam 78, which is reflected upward by a mirror 80 on a 45° angled surface of the base element 22. Mirror 80 is constructed to be nearly 100 percent reflective. The laser diode 76 is supported by a mounting block ~~82~~ 81 that enables precise alignment of the light beam 78 with the mirror 80. The light beam 78, after reflection by the mirror 80, passes through the base element 22 and enters the lens element 12 just beneath the slot 14. The light beam 78 is substantially reflected by the mirror 28 in the slot 14 back to the right in the view of Figure 4 horizontally at the mirror 36. Mirror 28 is oriented as a 45° angle to reflect the upwardly directed beam horizontally (or longitudinally with respect to the lens element 12) at the mirror 36.